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Fig. 1

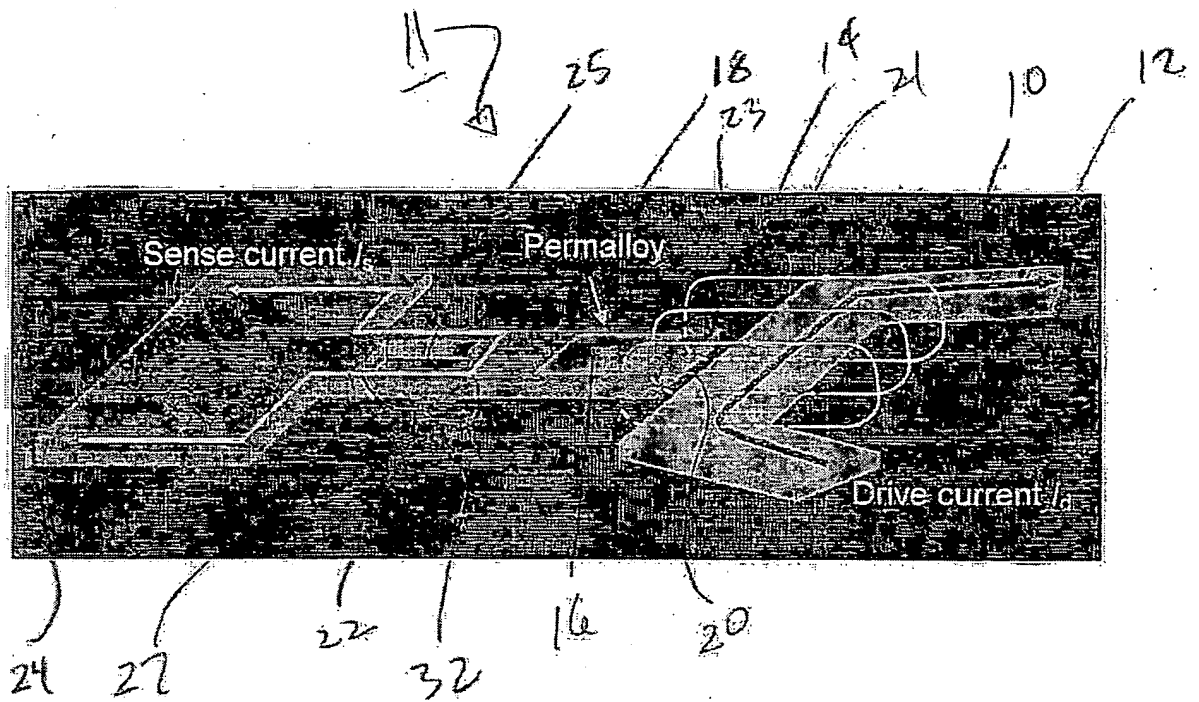


Fig. B

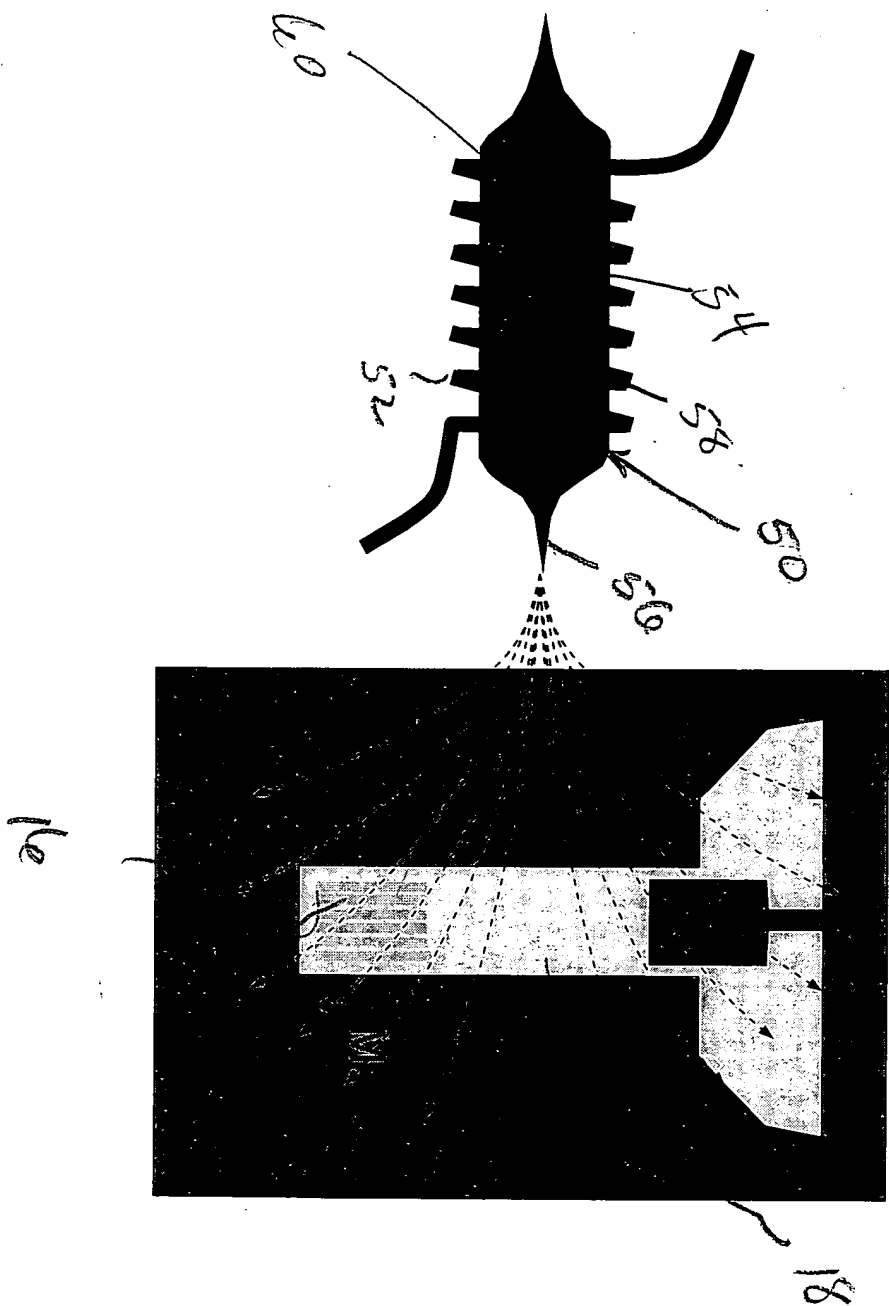


Fig. 4(a)

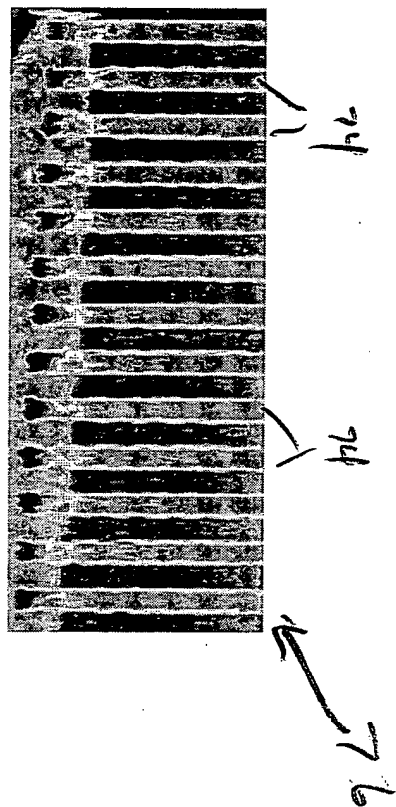
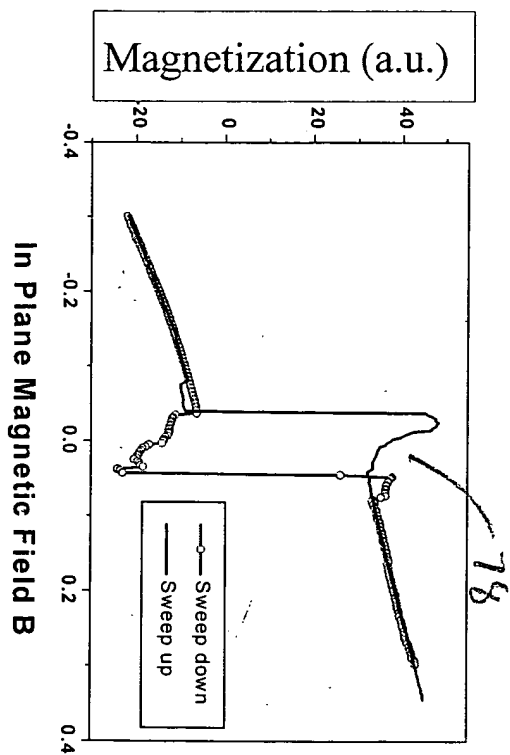
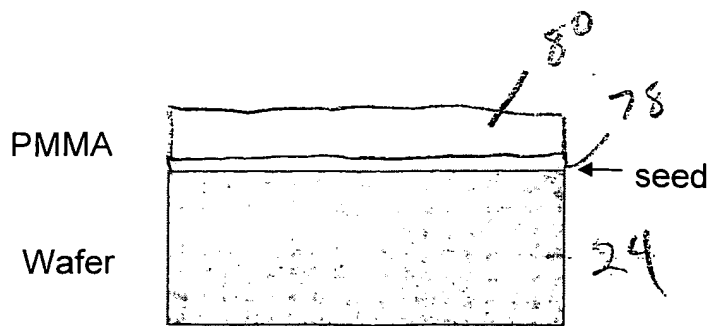
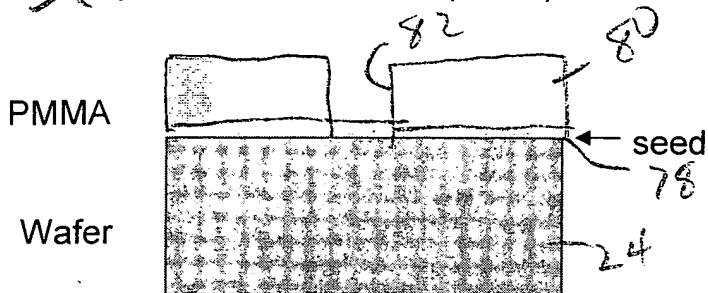


Fig. 4(b)

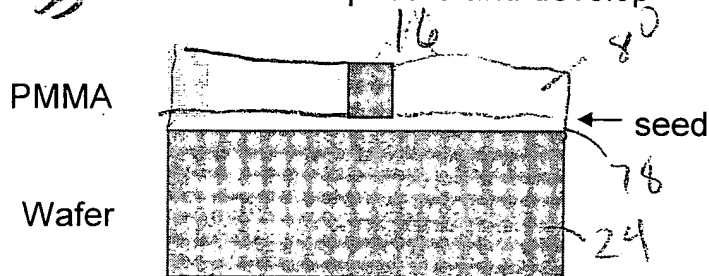




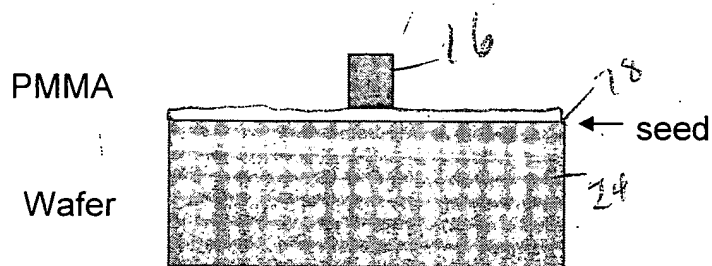
51 Spin coat thick PMMA (~2um)



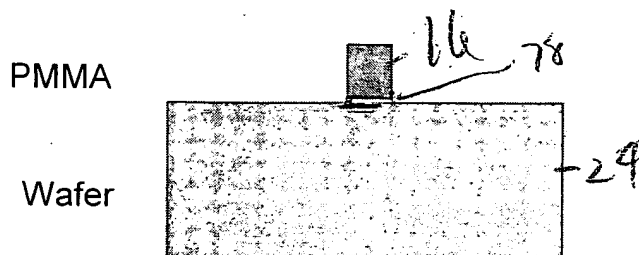
52 Electro beam exposure and develop



53 Electro beam exposure and develop



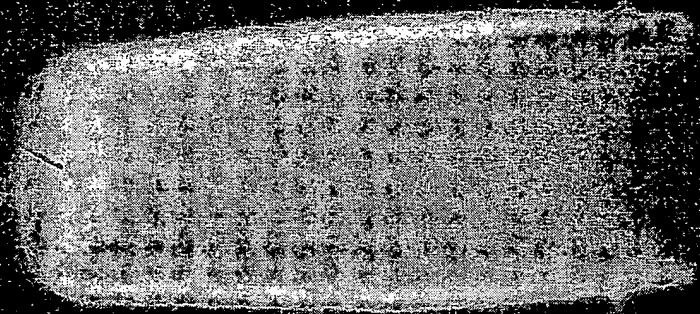
54 Stripe off PMMA



55 Dry etch seed metal layer

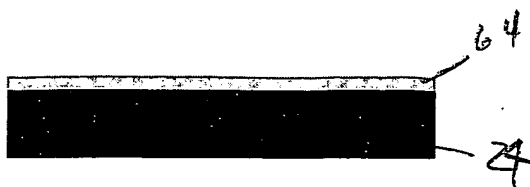
Fig. 5f

/16



CIT 40KV 12m X20,000 45mm

Fig. 6a



Cu or coating 30 nm

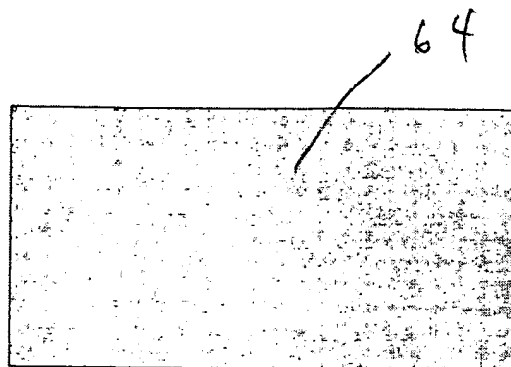
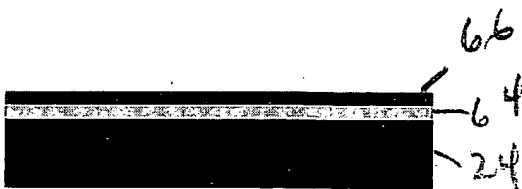


Fig. 6b



Insulator deposition 1um
SiN or cured photoresist

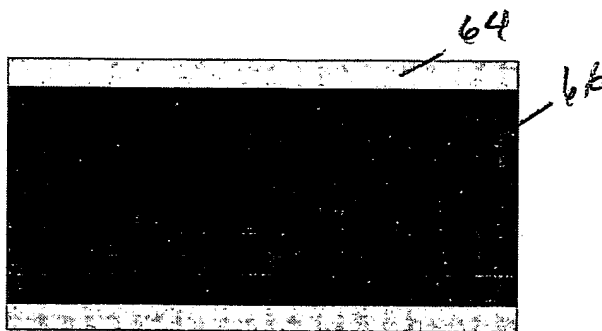
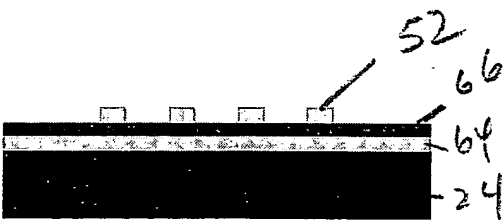


Fig. 6c



Bottom conductor
Plating, Cu or Au 1um

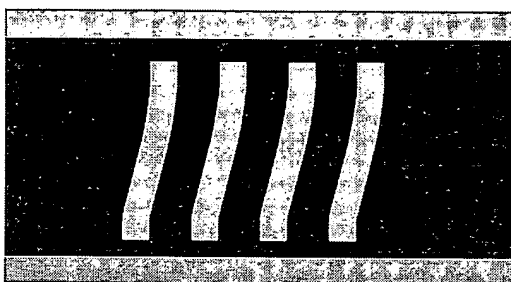
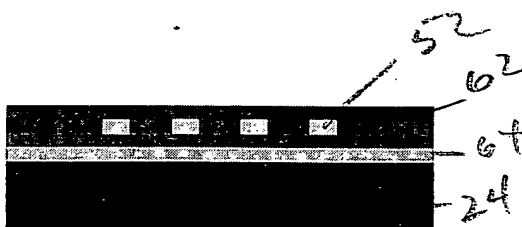


Fig. 6d



1um Cured Photoresist
Or PECVD SiO2

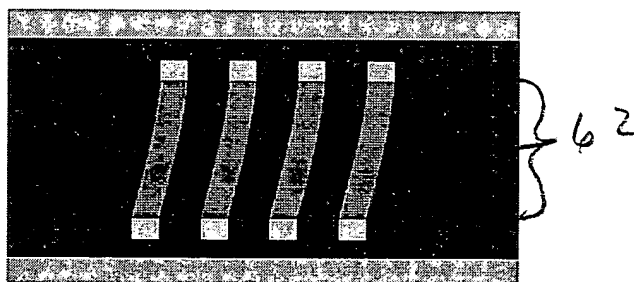
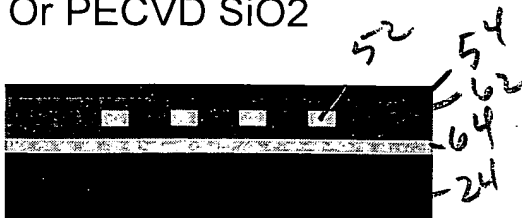


Fig. 6e



Electroplate 1um Ni core

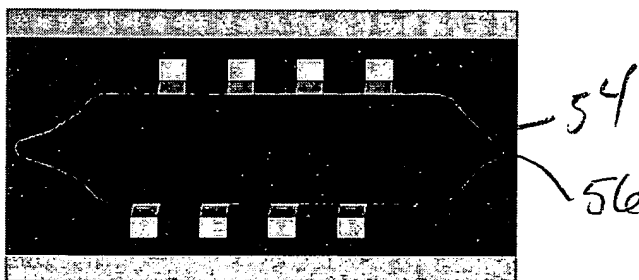
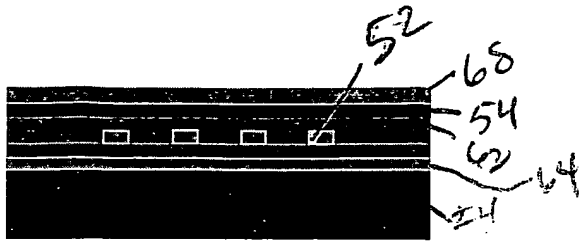
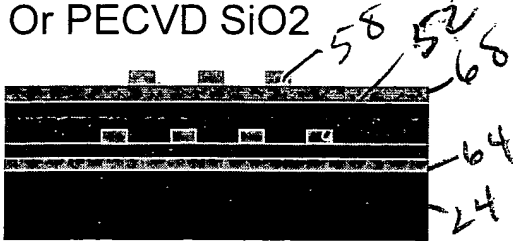


Fig. 6f



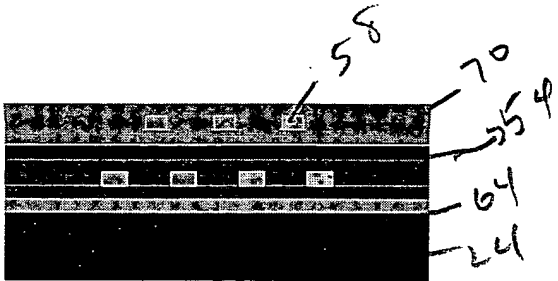
1um cured Photoresist
Or PECVD SiO₂

Fig. 6g



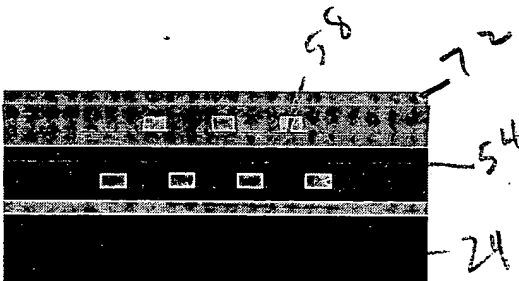
Electroplate Cu or Au

Fig. 6h



Cap Photoresist or SiO₂

Fig. 6i



Cap with metal/SiN for electrical
shielding / passivation

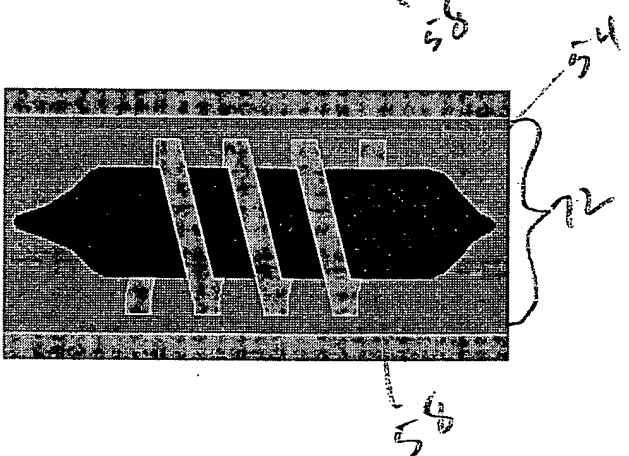
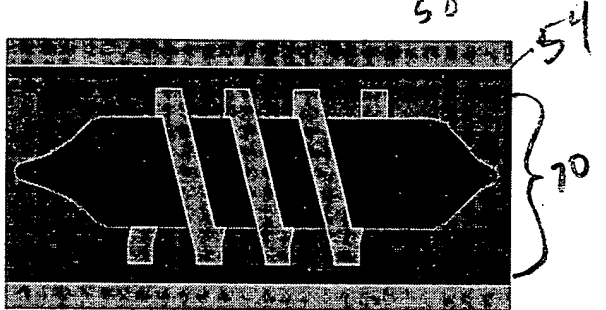
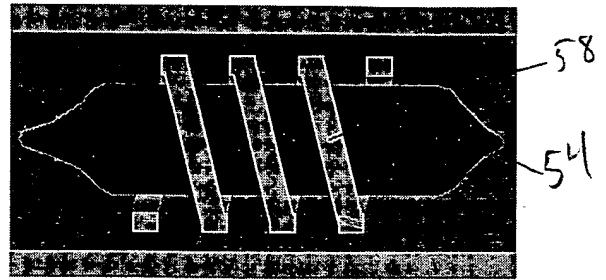
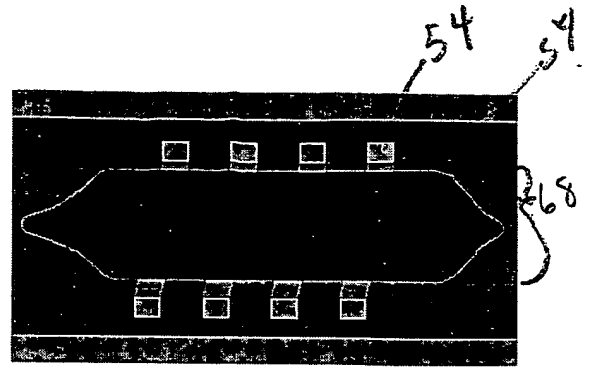


Fig. 7

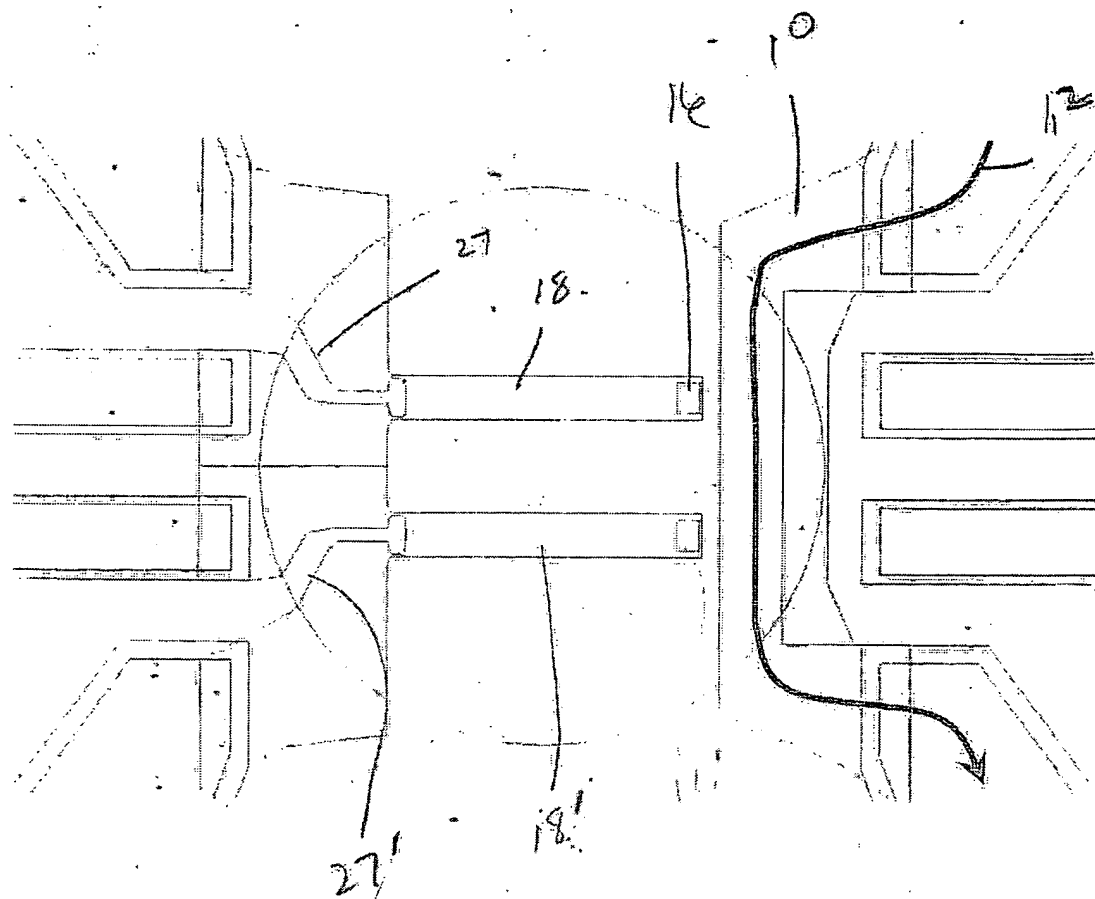


Fig. 8

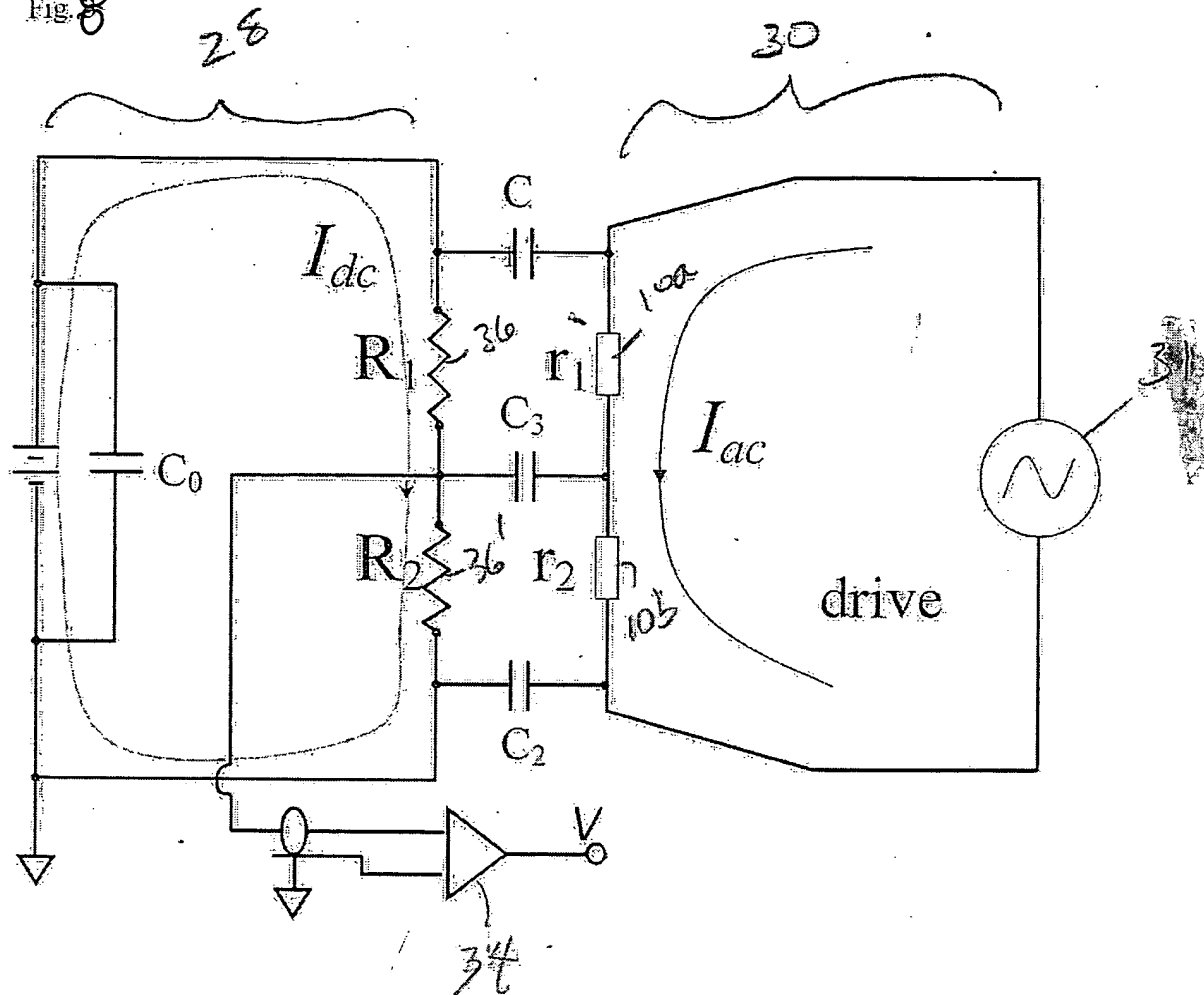


Fig. 9a

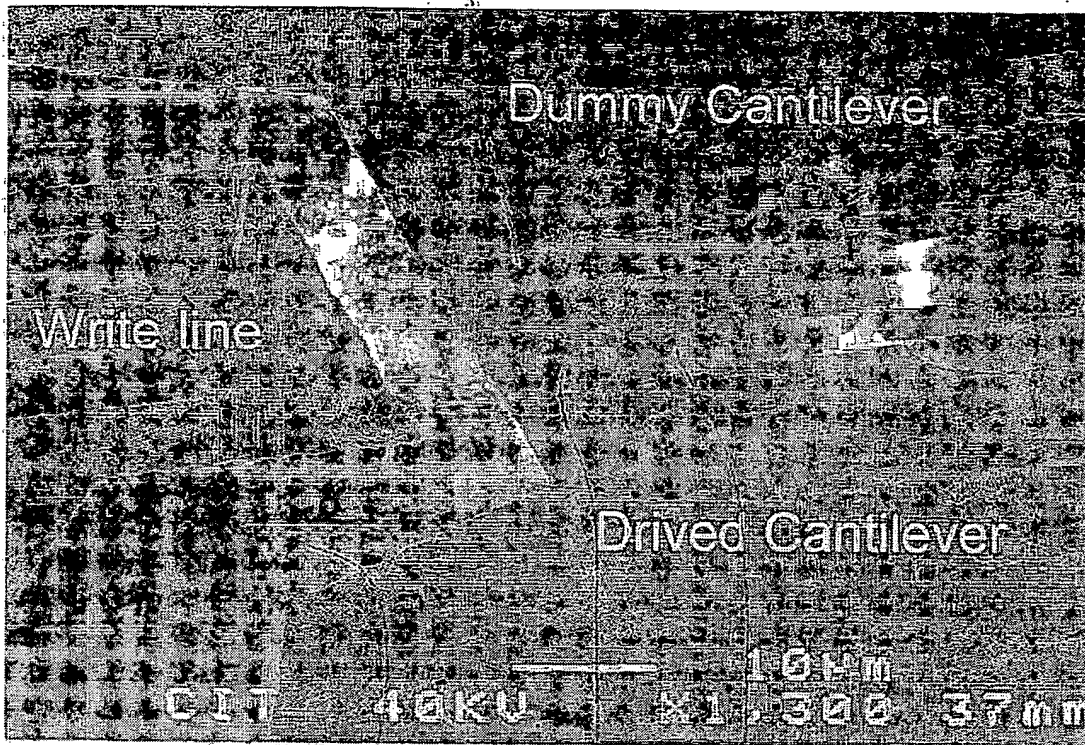


Fig. 9b

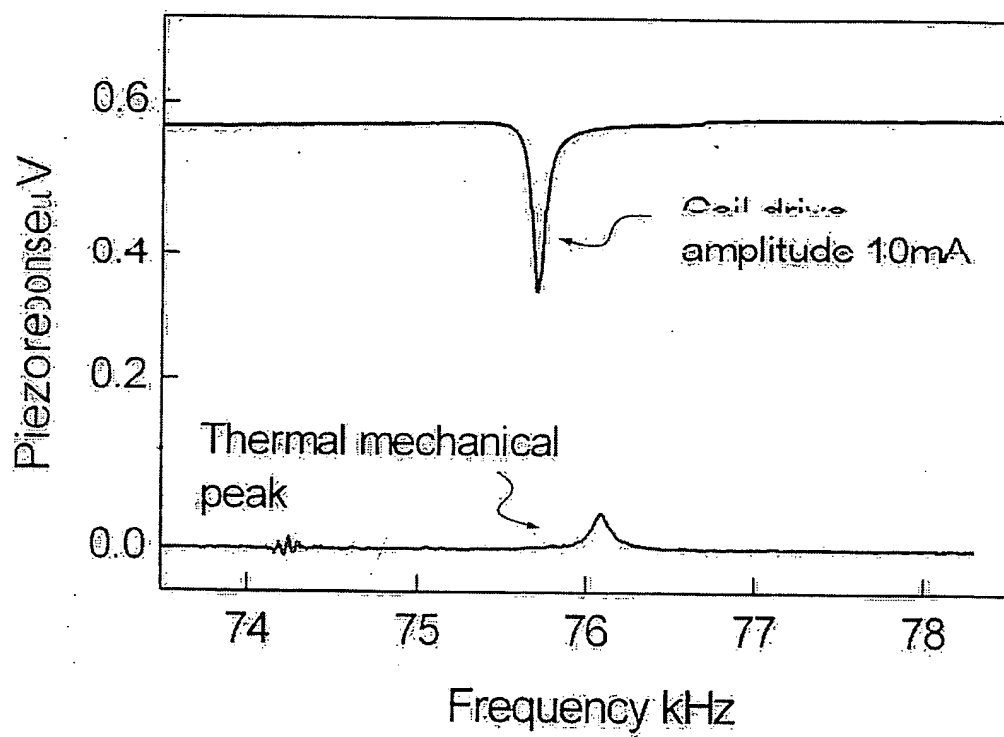


Fig. 10

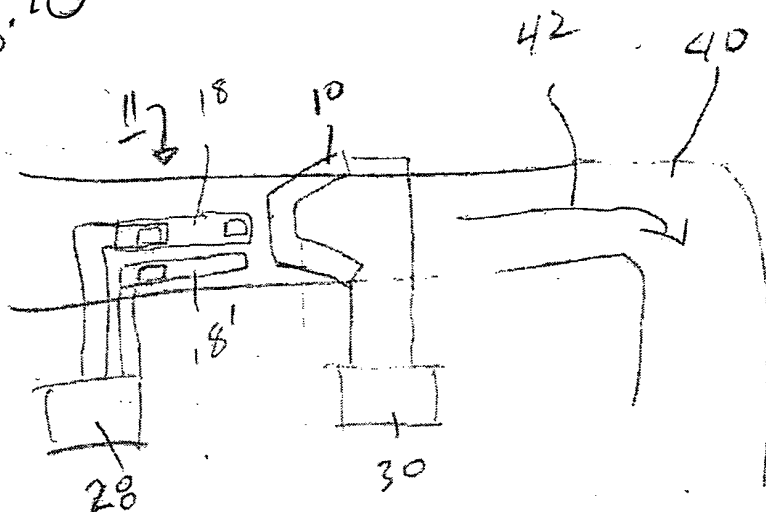


Fig. 11

